Embedded Building Blocks

Eurotech's embedded components are designed to match the needs of extremely demanding customers. Eurotech has a complete portfolio of boards and embedded modules with CPU processor based on the state of the art architectures: Intel Atom, Core, Xeon D and Arm. The boards are either CPU boards or single board computer - SBC - available in many form factors: COM-HPC, COM Express, Single Board Computers, VME, CompactPCI, PC/104 and low-power Small Form Factor.

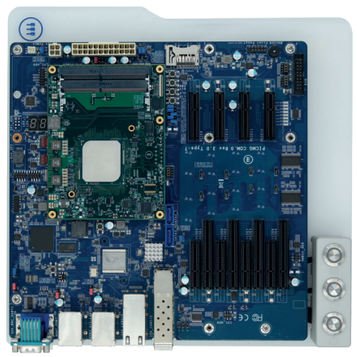
Eurotech complete portfolio of embedded processor, communication and I/O modules, is suitable for a range of applications including Industrial, Transportation, Defense, Infotainment and many others. In particular, Eurotech rugged boards powered by processors like the Intel Xeon D are a perfect fit for the emerging market of edge computing nodes and **High Performance Edge Computing (HPEC)** applications.

Development Kits
Great out-of-the-box experience

We offer a wide range of ready-to-use Development Kits to pair the chosen Single Board Computer or CPU module with the most popular operating systems.

Our development kits are quick to setup and to get ready to develop applications on embedded devices.

They help system integrators and OEMs to reduce time to market by essentially eliminating the driver development, OS development and middleware development.



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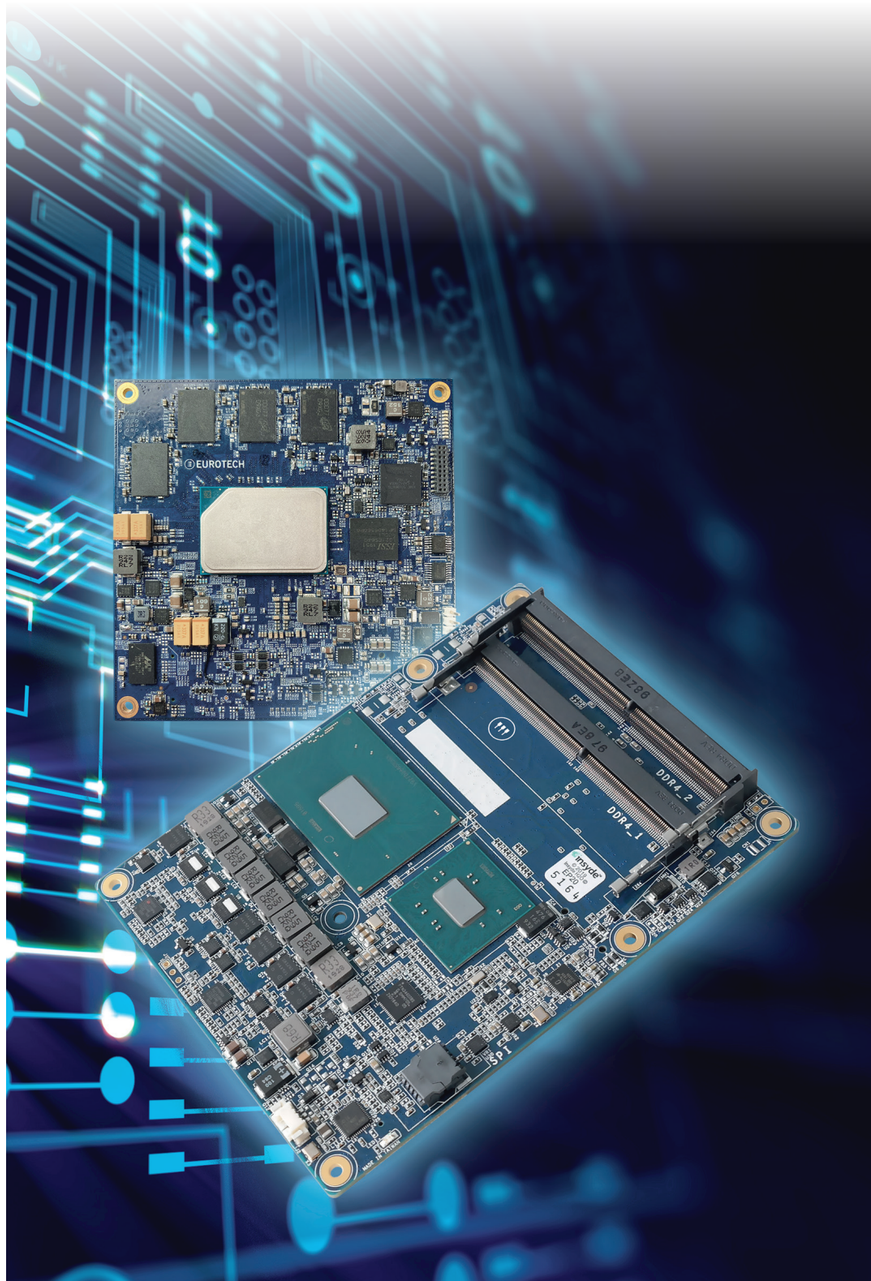
Imagine. Build. Succeed.

Embedded Boards and Modules



Board		Family	CPU	RAM	STORAGE	Ethernet	USB	Serial	CAN 2.0B	Digital I/O	Video	PCIe	Power	Op.Temp.
CPU-180-01		COM-HPC Client Size A	11th Generation Intel Core Core i3-1115GRE, up to 3.0GHz, 2 Cores Core i5-1145GRE, up to 2.6GHz, 4 Cores Core i7-1185GRE, up to 2.8GHz, 4 Cores	Up to 32GB LPDDR4 IBECC	2x SATA 3.0	1x 2.5GbE with TSN	2x USB3/4/C 8x USB2.0	2x UART	-	12	1x DDI 1x DDI eDP 2x Thunderbolt 4	1x PCIe x4 Gen4 4x PCIe x1 Gen3 1xPCIe x4 Gen3 1xPCIe x1 Gen3	12~28W CPU TDP	-40 to +85°C
CPU-180-02		COM-HPC Client Size A - like for Functional Safety	11th Generation Intel Core Core i5-1145GRE, up to 2.6GHz, 4 Cores Core i7-1185GRE, 2.8/1.8/1.2GHz, 4 Cores	Up to 32GB LPDDR4 IBECC	2x SATA 3.0	1x 2.5GbE with TSN	4x USB3/4/C 10x USB2.0	2x UART	-	12	1x DDI 1x DDI eDP 2x Thunderbolt 4	1x PCIe x4 Gen4 4x PCIe x1 Gen3 1x PCIe x4 Gen 3 1x PCIe x1 Gen3	12-28W CPU TDP	-40 to +85°C
CPU-161-19		COM Express Compact Type 6	Intel Atom x6000 Series Atom x6212RE 1.20GHz, 2 Cores Atom x6414RE 1.50GHz, 4 Cores Atom x6425RE 1.90GHz, 4 Cores	Up to 16GB DDR4 IBECC	1x SPI-Flash 2x SATA 3.0	1x 2.5GbE with TSN 2x SGMII 10/100/1000/2500Mbps (∞)	2x USB3.0 8x USB2.0	2x UART 3x UART 2-wire + 5x UART 4-wire (∞)	2 (∞)	8	2x DDI 1x LVDS	1x PCIe x4 Gen3 (or 2x PCIe x2 Gen3, or 4x PCIe x1 Gen3) 2x PCIe x1 Gen3	6-12W CPU TDP	-40 to +85°C
CPU-161-20		COM Express Compact Type 6 - like for Functional Safety	Intel Atom x6000 Series Atom x6200FE 1.00GHz, 2 Cores Atom x6427FE 1.90GHz, 4 Cores	Up to 16GB DDR4 IBECC	1x SPI-Flash 2x SATA 3.0	1x 2.5GbE with TSN 2x SGMII 10/100/1000/2500Mbps (∞)	2x USB3.0 8x USB2.0	3x UART 2-wire 5x UART 4-wire	2	8	2x DDI 1x LVDS	1x PCIe x4 Gen3 (or 2x PCIe x2 Gen3, or 4x PCIe x1 Gen3) 2x PCIe x1 Gen3 (Mutually Exclusive with SGMII)	4.5-12W CPU TDP	-40 to +85°C
CPU-161-18		COM Express Compact Type 6	Intel Xeon D Pentium D1519 1.50GHz, 4 Cores Xeon D-1529 1.30GHz, 4 Cores Xeon D-1539 1.60GHz, 8 Cores Xeon D-1559 1.50GHz, 12 Cores	8GB DDR4 ECC 1x DDR4 ECC SODIMM up to 16GB (On-socket)	Up to 4x SATA 3.0	1x 1GbE	Up to 4x USB 3.0 Up to 7x USB 2.0	2x UART	-	8	-	1x PCIe x16 Gen 3 4x PCIe x1 Gen 2 1x PCIe x4 Gen 2	20-45W CPU TDP	-40 to +85°C
CPU-163-16		COM Express Mini Type 10	Intel Atom E3900 E3930 1.30/1.80GHz, 2 Core E3940 1.60/1.80GHz, 4 Cores E3950 1.60/2.00GHz, 4 Cores	Up to 8GB ECC DDR3L	Up to 64GB eMMC 2x SATA 3.0	1x 1GbE	2x USB3.0 8x USB2.0	2x Serial	-	SDIO (GPIO ∞)	1x DDI 1x LVDS/eDP	4x PCIe x1 Gen 2	6.5-12W CPU TDP	-40 to +85°C
CPU-163-15		COM Express Mini Type 10	IIntel Atom E3800 E3815 1.46GHz, 1 Core E3827 1.75GHz, 2 Cores E3845 1.91GHz, 4 Cores	Up to 4GB DDR3L-ECC	8GB eMMC 2x SATA 2.0	1x 1GbE	1x USB 3.0 8x USB 2.0	2x Serial	-	8	1x DDI	3x PCIe x1 (Gen 2)	5-10W CPU TDP	Up to -40 to +85°C
CPU-162-23		COM Express Basic Type 7	Intel Xeon D Pentium D1519 – 1.50GHz, 4 Cores Xeon D-1539 – 1.60GHz, 8 Cores Xeon D-1559 – 1.50GHz, 12 Cores Xeon D-1567 – 2.10GHz, 12 Cores Xeon D-1577 – 1.30GHz, 16 Cores	3x DDR4-ECC SODIMM Up to 48GB	2x SATA 3.0	2x 10GbE 1x 1GbE	4x USB 3.0 4x USB 2.0	2x UART	-	8	-	1x PCIe x16 (Gen 3) 1x PCIe x8 (Gen 3) 1x PCIe x4 (Gen 2) 1x PCIe x2 (Gen 2) 1x PCIe x1 (Gen 2)	25-45W CPU TDP	Up to -40 to +85°C
CPU-162-24		COM Express Basic Type 6	Xeon E3-1500 Xeon E3-1505L v6 up to 3.00GHz, 4 Cores Xeon E3-1505M v6 up to 4.00GHz, 4 Cores	2x DDR4-ECC SODIMM Up to 32GB	4x SATA 3.0	1x 1GbE	4x USB 3.0 8x USB 2.0	2x UART	-	8	1x VGA 1x LVDS 2x DDI	1x PCIe x16 or 2x PCIe x8 (Gen 3) 8x PCIe x1 or 2x PCIe x4 or 4x PCIe x3 (Gen 3)	25-45W CPU TDP	-40 to +85°C
CPU-310-12		Singole Board Computer	TI AM3352 1GHz, 1Core	1GB DDR3	8GB eMMC	2x 10/100Mbps	3x USB 2.0	1x RS-485 1x RS-232/485 1x TTL Console	2	4	-	-	2-15W CPU TDP	-30 to +70°C
CPU-301-16		Small Form Factor Ultra Low Power	NXP i.MX6Solo NXP i.MX6DualLite NXP i.MX6Dual NXP i.MX6Quad	Up to 4GB DDR3L	Up to 64GB eMMC 1x SATA 2.0	1x 1GbE	1x USB 2.0, OTG	1x RS-232 (2 wire)	2	21	1x HDMI	1x PCIe x1	1-2W (5W Max) CPU TDP	Extended: -40 to +85°C Commercial: 0 to +70°C
Catalyst BT		Small Form Factor Catalyst Module	Intel Atom E3800 E3815 1.46GHz, 1 Core E3827 1.75GHz, 2 Cores E3845 1.91GHz, 4 Cores	Up to 4GB DDR3L-ECC	8GB to 32GB SATA SSD Up to 2x SATA 2.0	1x 1GbE	8x USB 2.0	2x Serial	-	6	1x eDP/DP/HDMI/LVDS 1x eDP/DP/HDMI/VGA	3x PCIe x1 Gen 2	-	-40 to +85°C
Catalyst AL		Small Form Factor Catalyst Module	Intel Atom E3900 E3930 1.3GHz, Dual Core E3940 1.6GHz, Quad Core E3950 1.6GHz, Quad Core	Up to 8GB DDR3L ECC	Up to 8GB eMMC	1x 1GbE	2x USB 3.0 7x USB 2.0	2x High Speed with Flow Control 1x High Speed 1x Debug Port	-	Up to 9	1x LVDS 2x DDI	4x PCIe Gen 2	7-15W CPU TDP	-40 to +85°C

∞: Factory Build Option

Ready for IoT

Eurotech's boards and modules can be provided with Everyware Software Framework (ESF), an IoT Edge Framework that allows connectivity with Cloud IoT platforms to enable the development and deployment of IoT and Edge computing applications and the remote management of devices and systems in the field.

Professional Services

Eurotech strategy is based on products that comply to industry standards. However, some projects require an extra ingredient. Our personalization and configuration service allows a perfect match to any project needs, allowing customers to implement their own unique design.

Eurotech, with its own experienced embedded engineers, is available to work closely to customers and partners in order to understand these unique needs with a suite of consulting and professional services. Our engineering teams can develop tailor-made boards and systems using the same professional design approach that is used to create our standard portfolio.

Eurotech's professional services include:

- BIOS personalization
- carrier board design
- system development and production
- deep module customization
- conformal coating
- special testing and qualification